



# Compound Semiconductor Materials Europe TC Chapter Meeting Summary and Minutes

April 1st, 2025  
04:30 PM – 06:00 PM CEST  
Online

## TC Chapter Announcements

Next TC Chapter Meeting  
November 18-21, 2025, SEMICON Europa. Check [www.semi.org/en/standards](http://www.semi.org/en/standards) for the latest update.

## Table 1 Meeting Attendees

**Co-Chair:** Arnd Weber (SiCrystal), Christian Kranert (Fraunhofer IISB)

**SEMI Staff:** Kevin Nguyen (SEMI)

<i>Company</i>	<i>Last</i>	<i>First</i>
<i>Wolfspeed</i>	<i>Barbieri</i>	<i>Tom</i>
<i>Infinion Technologies Austria AG</i>	<i>Broxtermann</i>	<i>Mike</i>
<i>SOITEC</i>	<i>Cela</i>	<i>Enrica</i>
<i>Scientific Visual</i>	<i>Cheze</i>	<i>Caroline</i>
<i>WD Advanced Materials</i>	<i>Ciraldo</i>	<i>John</i>
<i>Infinion Technologies Austria AG</i>	<i>Fey</i>	<i>Julian</i>
<i>Fraunhofer IISB</i>	<i>Kranert</i>	<i>Christian</i>
<i>Freiberger Compound Materials GmbH</i>	<i>Kretzer</i>	<i>Ulrich</i>
<i>Self</i>	<i>Kronwasser</i>	<i>Judy</i>
<i>Wolfspeed</i>	<i>Rao</i>	<i>Shailaja</i>
<i>GlobalWafers</i>	<i>Sanna</i>	<i>Cristina</i>
<i>SiCrystal</i>	<i>Weber</i>	<i>Arnd</i>

*Italic* indicates online participant. **Bold** indicates in-person attendance.

## Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
<i>None</i>		

## Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
<i>None</i>	

**Table 4 Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7280	Line-Item Revision to SEMI M83-0820 Test Method For Determination Of Dislocation Etch Pit Density In Monocrystals Of Iii-V Compound Semiconductors	Refer below.
	Line Item 1 - Editorial changes	Passed as balloted
	Line Item 2 - Change Etching time in Table 1 and 2	Passed as balloted
	Line Item 3 - Update section 9	Passed as balloted

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 5 Ratification Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&amp;R Action</i>	<i>A&amp;R Forms</i>
R7225	New Standard: Specification for Silicon Carbide Engineered Substrates	Approved, pending publication	

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 6 Authorized Activity**

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

#1 SNARFs and TFOFs are available for review on the SEMI web site at: <http://downloads.semi.org/web/wstdsbal.nsf/tfofsnarf>

**Table 7 Authorized Ballots**

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
None			

**Table 8 New Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
None		

**Table 9 Previous Meeting Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>	<i>Status</i>
None			

## 1 Welcome, Reminders, and Introductions

1.1 Arnd Weber called the meeting to order at 04:30 PM. Attendees introduced themselves. Kevin Nguyen presented meeting reminders on antitrust, intellectual property issues and effective meeting guidelines.

## 2 Review of Previous Meeting Minutes

2.1 The TC Chapter reviewed the minutes of the previous meeting.

**Motion:** To approve the meeting minutes  
**By / 2<sup>nd</sup>:** By: Christian Kranert / Fraunhofer IISB  
Second: Shailaja Rao / Wolfspeed  
**Discussion:** None  
**Vote:** 10-0. Motion passed.

## 3 Task Force Reports

### 3.1 *SiC-Task Force*

3.1.1 Arnd Weber reported the TF has been reviewing SEMI M81, Guide to Defects Found in Monocrystalline Silicon Carbide Substrates. Little progress is made, due to lack of resources.

### 3.2 *5-year Review Task Force*

3.2.1 The TF leader is not available. No report.

### 3.3 *Test Methods Task Force*

3.3.1 Christian Kranert reported no activity.

### 3.4 *SIC Epi-Defects Task Force*

3.4.1 Christian Kranert reported on the progress made regarding Document 7160, New Standard: Guide for Defects Found in Homoepitaxial Layers of Silicon Carbide. The topic is complex, but the task force has been meeting regularly.

### 3.5 *Silicon Carbide Engineered Substrate Task Force*

3.5.1 Enrica Cela reported that the Ratification Ballot for Document R7233, New Standard: Specification for Silicon Carbide Engineered Substrate, has passed. Publication is pending. Kevin will forward the proof copy once the draft has been processed by Publications.

## 4 Ballot Review

4.1 Doc. 7280, Line Item Revision of SEMI M83-0820, Test Method for Determination of Dislocation Etch Pit Density in Monocrystals of III-V Compound Semiconductors

4.1.1 Passed as balloted. Refer to attachment for details.

**Attachment: 7280 Procedural Review**

## 5 Liaison Reports

### 5.1 NA CSM TC Chapter

5.1.1 Kevin Nguyen reported the TC Chapter has not been meeting for a while. However, the NA Co-chairs would like to remain open to monitor progress in other regions.

### 5.2 China CSM TC Chapter

5.2.1 Kevin Nguyen reported. Of note:

- Last meeting
  - Dec 6, 2024
- Next meeting
  - June 2025
- SNARFs granted one year extension.
  - Doc. 6767, TEST METHOD FOR GBIR, SBIR, SFQR and SORI OF SILICON CARBIDE WAFERS BY OBLIQUE INCIDENT INTERFERENCE METHOD
  - Doc. 6769, TEST METHOD FOR RESIDUAL STRESS OF SILICON CARBIDE WAFERS BY PHOTOELASTIC EFFECT
- Authorized Activities
  - New Standard: Specification of Multiple Materials Substrate for GaN Epitaxial Growth for HB-LED
  - New Standard: Specification of High Purity Silicon Carbide Powder for SiC Crystal
- Authorized Ballot in cycle 2-2025
  - Doc. 6769C, New Standard: Test Method for Residual Stress of Silicon Carbide Wafers by Photoelastic Effect

### **Attachment: CSM China TC Chapter Liaison Report Dec 2024**

### 5.3 Japan CSM TC Chapter

5.3.1 Kevin Nguyen reported. Of note:

- Last meeting
  - Thursday, December 12, 2024
  - SEMICON Japan 2024
- Next meeting
  - Monday, June 30, 2025
  - SEMI Japan, Tokyo, Japan + OVTCCM (Hybrid)
- Authorized Ballot
  - Doc. 7211A, Line Item Revision to SEMI M92-0423, Specification for 4H-SiC Homoepitaxial Wafer
- SiC Epitaxial Wafer Liaison Task Force



- Considers including 200.0 mm 4H-SiC epitaxial wafers in SEMI M92, Specification for 4H-SiC Homoepitaxial Wafer by submitting another SNARF.

**Attachment: CSM\_JA TC Chapter Liaison Report\_March 2025\_R1**

**6 New Business**

6.1 5 year review

6.1.1 Arnd presented a list of documents due for five-year review under the Europe Compound Semiconductor program. One of these is \*SEMI M82-0820, Test Method for the Carbon Acceptor Concentration in Semi-Insulating Gallium Arsenide Single Crystals by Infrared Absorption Spectroscopy, which is approaching its five-year review deadline. Christian noted that the update may only require a line-item revision. Arnd will review the document and may prepare a SNARF at the next meeting.

6.2 Kevin Nguyen suggested that members consider developing a program related to Compound Semiconductor Materials or education on new Standards. This could take the form of a webinar or an in-person event.

6.2.1 Arnd stated that he would consider the technical aspects, including the properties and physics of silicon carbide, and how these elements could be integrated into a cohesive program. This item may be placed on the next committee’s agenda.

**7 Next Meeting and Adjournment**

7.1 The next meeting is scheduled for November, 2025 in conjunction with SEMICON Europa in Munich, Germany. Arnd requested to avoid other program being taken place at SEMICON Europe. Refer to <http://www.semi.org/standards> for the list of meeting schedules.

Having no further business, adjournment was at 6:00 PM CEST.

Respectfully submitted by:

Kevin Nguyen,  
SEMI Standards Operations Manager  
Phone: 408-943-7997  
Email: [knguyen@semi.org](mailto:knguyen@semi.org)

Minutes tentatively approved by:

Arnd Weber (SiCrystal)	
Christian Kranert (Fraunhofer IISB)	

**Table 10 Index of Available Attachments#1**

<i>Title</i>
7280 A&R
R7225 A&R
CSM China TC Chapter Liaison Report Dec 2024
CSM_JA TC Chapter Liaison Report_March 2025_R1

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.